


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	AMS/19/11488	
<b>1.3 Title of PCN</b>	VIPOWER M03 products (VN8601 Line) in PowerSO 20 and PowerSO-10 package: ST Ang Mo Kio (Singapore) as Additional Wafer FAB. New BOM on SO20 Package.	
<b>1.4 Product Category</b>	See product list	
<b>1.5 Issue date</b>	2019-04-29	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Domenico ARRIGO
<b>2.1.2 Marketing Manager</b>	Fulvio PULICELLI
<b>2.1.3 Quality Manager</b>	Alessandro PLATINI

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	Wafer Fab (DIFF): CATANIA (CT6F) and ST Ang Mo Kio (AM6F) (Singapore) ASSY Plant: ST MUAR - MALAYSIA

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Wafer Fab (DIFF): CATANIA (CT6F) BOM in PowerSO 20 package: No GREEN Molding Compound and LeadFrame 24 units/matrix.	Wafer Fab (DIFF): Singapore-ST Ang Mo Kio (AM6F) BOM in PowerSO 20 package: GREEN Molding Compound and IDF LeadFrame 48 units/matrix
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No Impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	The transfer to ST Ang Mo Kio (Singapore) as additional Wafer Fab (DIFF) for the selected VIPOWER M03 products in both packages, PowerSO 20 and PowerSO-10, guarantees more flexibility in term of manufacturing and anticipates the termination of the same manufacturing in Catania as Wafer Fab (DIFF) for the selected products. Furthermore, referring to PowerSO 20 package, the change of LF is done for cost saving and the change of Molding Compound is done for meeting better enviromemntal requirements.
<b>5.2 Customer Benefit</b>	MANUFACTURING FLEXIBILITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	New FGs
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2019-06-10
<b>7.2 Intended start of delivery</b>	2019-07-31
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	
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8.2 Qualification report and qualification results	In progress	Issue Date	
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<b>9. Attachments (additional documentations)</b>
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11488 Public product.pdf
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<b>10. Affected parts</b>
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	VNQ860-E	
	VNQ860SPTR-E	
	VNQ860TR-E	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** VIPOWER M03 products (VN8601 Line) in PowerSO 20 and PowerSO-10 package: ST Ang Mo Kio (Singapore) as Additional Wafer FAB. New BOM on SO20 Package.

**PCN Reference :** AMS/19/11488

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

VNQ860-E	VNQ860TR-E	VNQ860SPTR-E
VNQ860SP-E		



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